

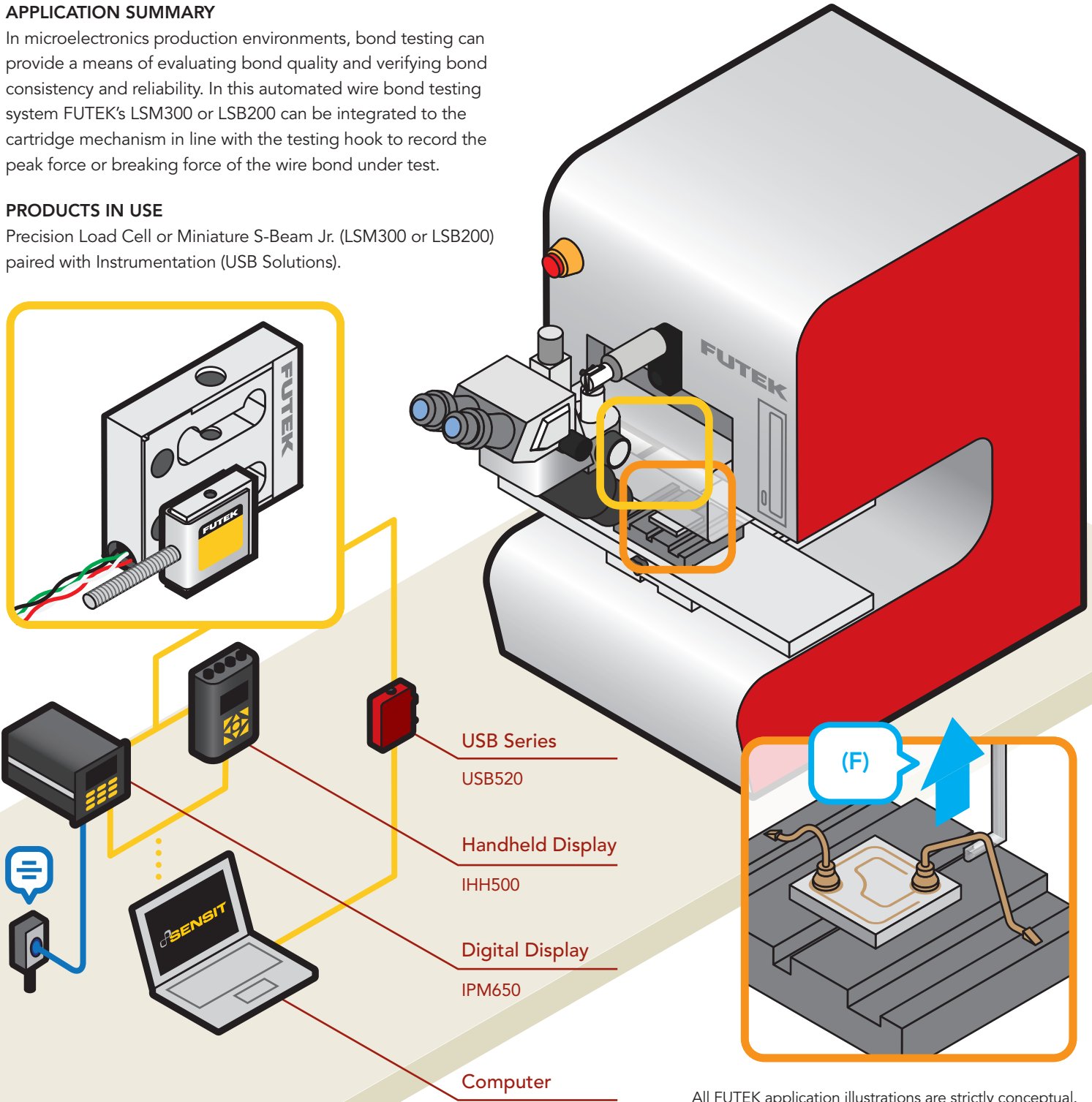


APPLICATION SUMMARY

In microelectronics production environments, bond testing can provide a means of evaluating bond quality and verifying bond consistency and reliability. In this automated wire bond testing system FUTEK's LSM300 or LSB200 can be integrated to the cartridge mechanism in line with the testing hook to record the peak force or breaking force of the wire bond under test.

PRODUCTS IN USE

Precision Load Cell or Miniature S-Beam Jr. (LSM300 or LSB200) paired with Instrumentation (USB Solutions).



All FUTEK application illustrations are strictly conceptual.
Please contact us with questions.